

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-2. (canceled)

3. (currently amended) A resistor substrate comprising: a resistor layer containing a powdered conductive material which is dispersed in a heat-cured resin; and an electrode layer containing a powdered metal which is dispersed in a heat-cured resin, in which the resistor layer is exposed at the topmost surface of the resistor substrate, the electrode layer is provided under the resistor layer, and the resistor layer and the electrode layer are supported by the substrate,

wherein the resin of the electrode layer has a thermosetting temperature lower than that of the resin of the resistor layer, and ~~The resistor substrate according to Claim 1,~~

wherein the thermosetting temperature of the resin of the resistor layer is different from that of the resin of the electrode layer by 30°C or more.

4. (currently amended) A resistor substrate comprising: a resistor layer containing a powdered conductive material which is dispersed in a heat-cured resin; and an electrode layer containing a powdered metal which is dispersed in a heat-cured resin, in which the resistor layer is exposed at the topmost surface of the resistor substrate, the electrode layer is provided under the resistor layer, and the resistor layer and the electrode layer are supported by the substrate,

wherein the resin of the electrode layer has a thermosetting temperature lower than that of the resin of the resistor layer, and ~~The resistor substrate according to Claim 1,~~

wherein the thermosetting temperature of the resin of the electrode layer is lower than a glass transition temperature of the resin of the resistor layer.

5. (currently amended) A resistor substrate comprising: a resistor layer containing a powdered conductive material which is dispersed in a heat-cured resin; and an electrode layer containing a powdered metal which is dispersed in a heat-cured resin, in which the resistor layer is exposed at the topmost surface of the resistor substrate, the electrode layer is provided under the resistor layer, and the resistor layer and the electrode layer are supported by the substrate,

wherein the resin of the electrode layer has a thermosetting temperature lower than that of the resin of the resistor layer, and ~~The resistor substrate according to Claim 1,~~

wherein the resin of the resistor layer is at least one selected from the group consisting of a thermosetting polyimide, a thermosetting poly(ether ketone), and a thermosetting bismaleimide, and the resin of the electrode layer is at least one selected from the group consisting of a phenolic resin, an epoxy resin, and a melamine resin.

6-12. (canceled)

13. (new) The resistor substrate according to Claim 3, wherein the thermosetting temperature of the resin of the electrode layer is lower than a glass transition temperature of the resin of the resistor layer.

14. (new) The resistor substrate according to Claim 3, wherein the resin of the resistor layer is at least one selected from the group consisting of a thermosetting polyimide, a thermosetting poly(ether ketone), and a thermosetting bismaleimide, and the resin of the electrode layer is at least one selected from the group consisting of a phenolic resin, an epoxy resin, and a melamine resin.

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